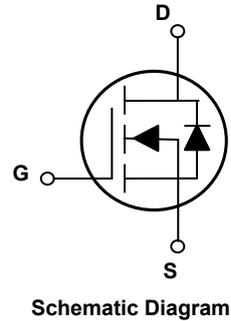
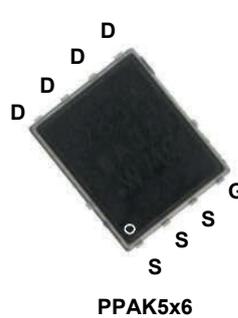


## Main Product Characteristics

$V_{(BR)DSS}$	60V
$R_{DS(ON)}$	9.7m $\Omega$ (Max.)
$I_D$	60A



## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery
- AEC-Q101 qualified



## Description

The GSGP9R706AU utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_C=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	60	A
Continuous Drain Current, @ Steady-State ( $T_C=100^\circ\text{C}$ )		42.5	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	240	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	96	W
Linear Derating Factor ( $T_C=25^\circ\text{C}$ )		0.64	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	81	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.56	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +175	$^\circ\text{C}$

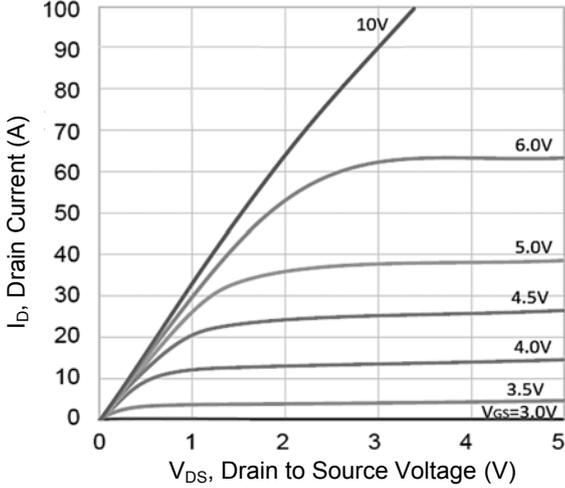
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=125^\circ C$	-	-	20	
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{GS}=20V$	-	-	100	nA
		$V_{GS}=-20V$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=13A$	-	8.0	9.7	m $\Omega$
		$V_{GS}=4.5V, I_D=11A$	-	11	14	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.7	2.5	V
Forward Transconductance	gfs	$V_{DS}=10V, I_D=6A$	-	12	-	S
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=30V, f=1MHz$	-	1064	2200	pF
Output Capacitance	$C_{oss}$		-	434	870	
Reverse Transfer Capacitance	$C_{rss}$		-	26	54	
Total Gate Charge	$Q_g$	$I_D=13A, V_{DS}=48V, V_{GS}=10V$	-	18	-	nC
Gate-to-Source Charge	$Q_{gs}$		-	5.6	-	
Gate-to-Drain ("Miller") Charge	$Q_{gd}$		-	2.7	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=30V, I_D=13A, R_{GEN}=3\Omega$	-	8.5	-	nS
Rise Time	$t_r$		-	52	-	
Turn-Off Delay Time	$t_{d(off)}$		-	18	-	
Fall Time	$t_f$		-	8.9	-	
Gate Resistance	$R_g$	$f=1MHz$	-	1.7	3	$\Omega$
<b>Drain-Source Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	60	A
Pulsed Source Current (Body Diode)	$I_{SM}$		-	-	120	A
Diode Forward Voltage	$V_{SD}$	$I_s=13A, V_{GS}=0V$	-	1	1.2	V
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C, I_F=13A, di/dt=100A/\mu s$	-	54	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	0.052	-	$\mu C$

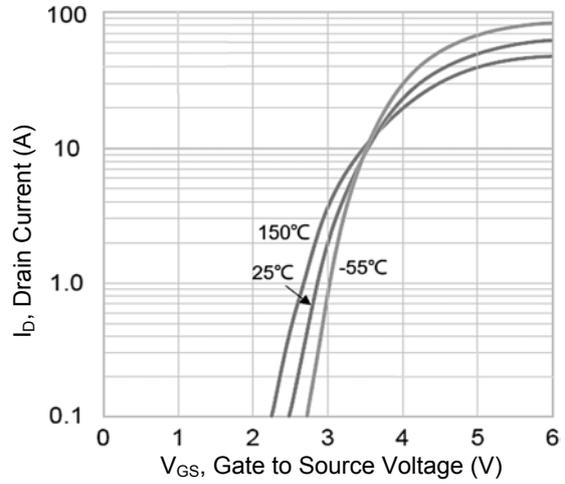
Notes:

1. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $L=0.5mH, R_G=10\Omega, V_{DD}=50V, T_J=25^\circ C$ .
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

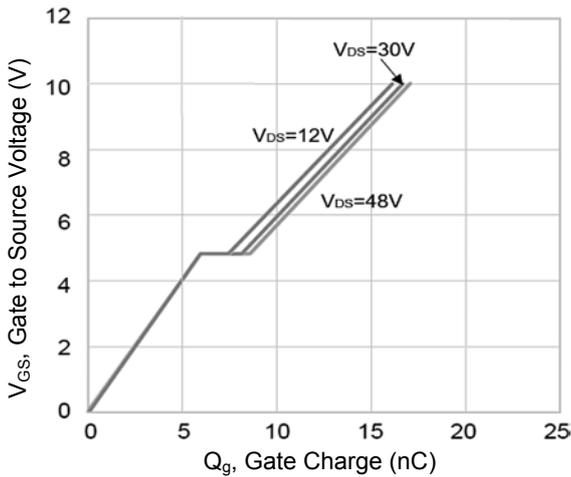
**Typical Electrical and Thermal Characteristic Curves**



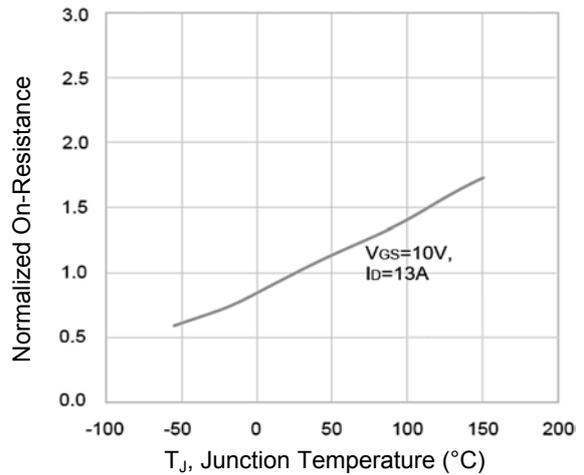
**Figure 1. Output Characteristics**



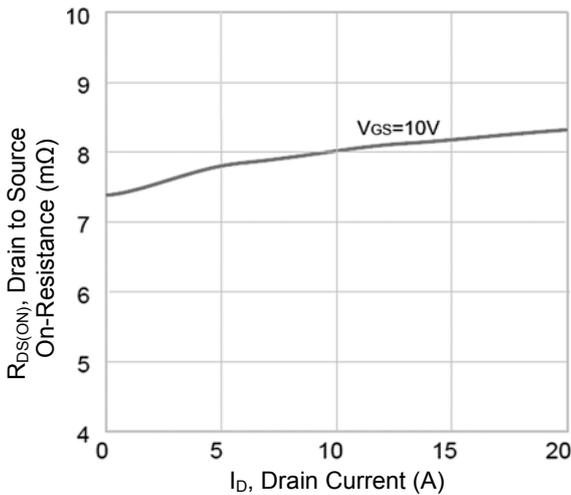
**Figure 2. Transfer Characteristics**



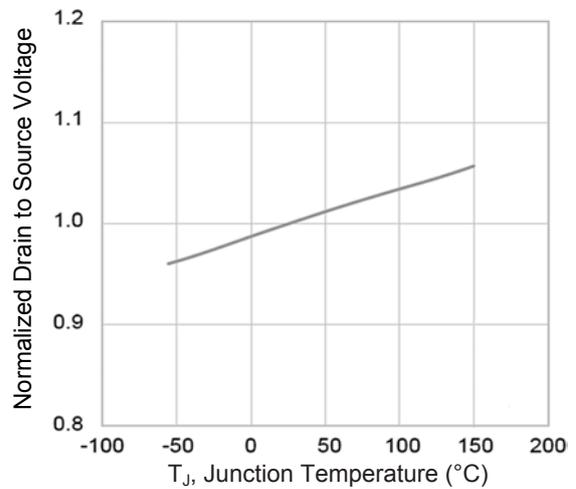
**Figure 3. Gate Charge**



**Figure 4. Normalized  $R_{DS(ON)}$  vs.  $T_J$**

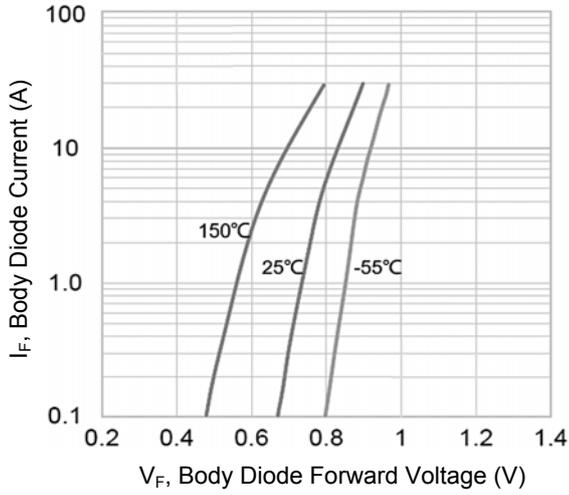


**Figure 5.  $R_{DS(ON)}$  vs.  $I_D$**

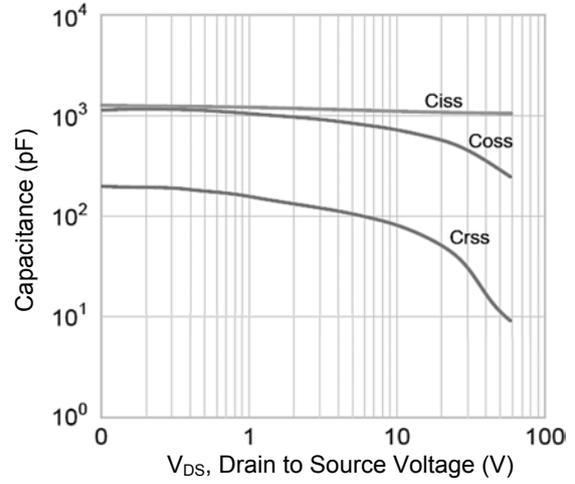


**Figure 6. Normalized  $BV_{DSS}$  vs.  $T_J$**

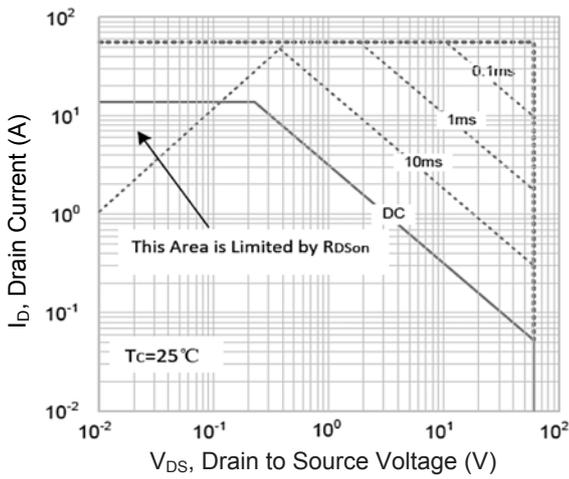
**Typical Electrical and Thermal Characteristic Curves**



**Figure 7. Body Diode Characteristics**

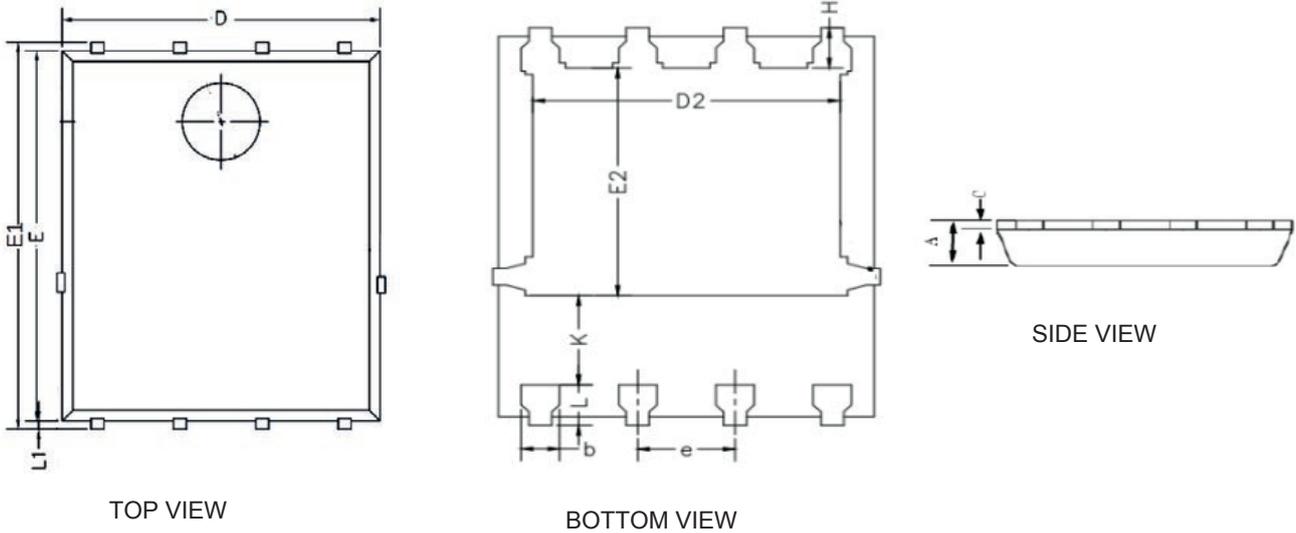


**Figure 8. Capacitance Characteristics**



**Figure 9. Safe Operation Area**

**Package Outline Dimensions (PPAK5x6)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.20	0.035	0.047
b	0.30	0.55	0.012	0.022
C	0.15	0.35	0.006	0.014
D	4.70	5.20	0.185	0.205
D2	3.76	4.20	0.148	0.165
E2	3.30	3.85	0.130	0.152
E	5.60	5.90	0.220	0.232
E1	5.80	6.20	0.228	0.244
K	1.10	-	0.043	-
H	0.45	0.75	0.018	0.030
L	0.45	0.75	0.018	0.030
L1	0.25	0.45	0.010	0.018
e	1.27 BSC		0.050 BSC	

**Order Information**

Device	Package	Marking	Packaging	SPQ
GSGP9R706AU	PPAK5x6	P9R706	Tape & Reel	5,000 Pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)